

MPS Rec'd PCT/PTO 31 JUL 2006

| Sheet 1 of 1 | | | INFORMATION DISCLOSURE STATEMENT | | | | |
|--|---------------|---|----------------------------------|--------------------|------------------------------------|----------|----------------------------|
| FORM PTO 1449 (<i>modified</i>) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE LIST OF REFERENCES CITED BY APPLICANT(S) <i>(Use several sheets if necessary)</i> Date Submitted to PTO: July 31, 2006 | | | ATTY DOCKET NO. 2006_0816A | | SERIAL NO. NEW 10/588108 | | |
| | | | APPLICANT Eiji UEDA | | | | |
| | | | FILING DATE July 31, 2006 | | GROUP | | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| *EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
| /KE/ | AA | 2002/0071303 | 6/2002 | Kund et al. | | | |
| /KE/ | AB | 2003-0212871 | 11/2003 | Suzuki et al. | | | |
| /KE/ | AC | 2001-0033012 | 10/2001 | Koemmerling et al. | | | |
| /KE/ | AD | 2004/0062115 | 4/2004 | Takeuchi et al. | | | |
| | AE | | | | | | |
| | AF | | | | | | |
| | AG | | | | | | |
| | AH | | | | | | |
| | AI | | | | | | |
| FOREIGN PATENT DOCUMENTS | | | | | | | |
| | | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION YES NO |
| /KE/ | AJ | 2003-91988 | 3/2003 | JP | | | Abstract |
| | AK | | | | | | |
| | AL | | | | | | |
| | AM | | | | | | |
| | AN | | | | | | |
| OTHER DOCUMENT(S) <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i> | | | | | | | |
| /KE/ | AO | K. Asari et al., "Ferroelectric Memory Circuit Technology and the Application to Contactless IC Card," IEICE TRANSACTIONS ON ELECTRONICS, Institute of Electronics Information and Comm. Eng., Tokyo, Japan, vol. E81-C, no. 4, April 1998 (4/1998), pp. 488-495, XP000833773 | | | | | |
| | AP | | | | | | |
| | AQ | | | | | | |
| EXAMINER | /Kevin Ellis/ | | DATE CONSIDERED | 03/20/2008 | | | |

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.